

# EMRA12M1J-3.6864M

[Click part number to visit Part Number Details page](#)

## REGULATORY COMPLIANCE (Data Sheet downloaded on Apr 3, 2020)



◀ Click badges to download compliance docs

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



## ITEM DESCRIPTION

MEMS Clock Oscillators LVCMOS (CMOS) 2.5Vdc 4 Pad 5.0mm x 7.0mm Plastic Surface Mount (SMD) 3.6864MHz ±20ppm over -40°C to +85°C

## ELECTRICAL SPECIFICATIONS

Nominal Frequency	3.6864MHz
Frequency Tolerance/Stability	±20ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, and Output Load Change)
Aging at 25°C	±1.5ppm Maximum First Year
Supply Voltage	2.5Vdc ±10%
Input Current	5mA Maximum (No Load)
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH = -3mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL = +3mA)
Rise/Fall Time	1.2nSec Typical, 3nSec Maximum (Measured from 20% to 80% of waveform)
Duty Cycle	50 ±10(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Power Down (Disabled Output: Logic Low)
Output Control Input Voltage Logic High (Vih)	70% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	30% of Vdd Maximum to Disable Output
Power Down Output Enable Time	5mSec Maximum
Power Down Output Disable Time	150nSec Maximum
Standby Current	10µA Maximum
Period Jitter (RMS)	2pSec Typical, 4pSec Maximum
RMS Phase Jitter (Fj = 900kHz to 7.5MHz; Random)	0.5pSec Typical, 1pSec Maximum
RMS Phase Jitter (Fj = 12kHz to 20MHz; Random)	1.5pSec Typical, 3pSec Maximum
Start Up Time	5mSec Maximum
Storage Temperature Range	-65°C to +150°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	JESD22-A114, HBM, 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition E, 10,000G
Moisture Sensitivity	J-STD-020, MSL 1
Solderability	MIL-STD-883, Method 2003 (Four I/O Pads on bottom of package only)
Temperature Cycling	JESD22-A104, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

## EMRA12M1J-3.6864M [Click part number to visit Part Number Details page](#)

### MECHANICAL DIMENSIONS (all dimensions in millimeters)

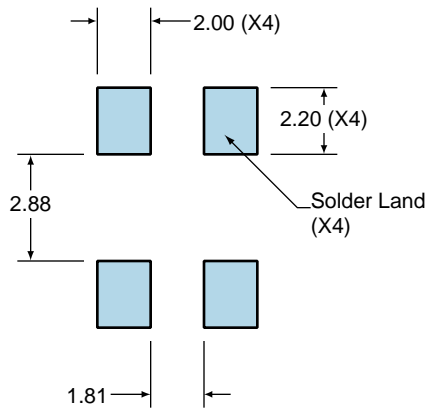


PIN	CONNECTION
1	Power Down (Logic Low)
2	Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	Ecliptek Manufacturing Identifier

### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

**EMRA12M1J-3.6864M** [Click part number to visit Part Number Details page](#)

**OUTPUT WAVEFORM & TIMING DIAGRAM**



# EMRA12M1J-3.6864M [Click part number to visit Part Number Details page](#)

## Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C<sub>L</sub> includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

# EMRA12M1J-3.6864M [Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b><math>T_S \text{ MAX}</math> to <math>T_L</math> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S \text{ MIN}$ )	150°C
- Temperature Typical ( $T_S \text{ TYP}$ )	175°C
- Temperature Maximum ( $T_S \text{ MAX}$ )	200°C
- Time ( $t_s \text{ MIN}$ )	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P \text{ Target}</math>)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperature shown are applied to body of device.

# EMRA12M1J-3.6864M [Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

Ts MAX to Tl (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
<b>Ramp-up Rate (Tl to Tp)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (Tl)	150°C
- Time (tL)	200 Seconds Maximum
<b>Peak Temperature (Tp)</b>	240°C Maximum
<b>Target Peak Temperature (Tp Target)</b>	240°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (tp)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperature shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperature shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperature shown are applied to body of device.)